

Description

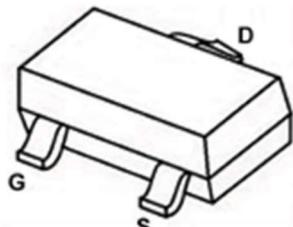
PECJ N-channel Enhancement Mode Power MOSFET

Features

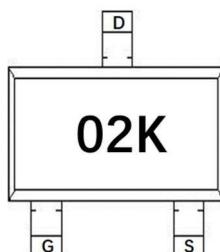
- 20V, 0.75A
- $R_{DS(ON)} < 380\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$
- $R_{DS(ON)} < 450\text{m}\Omega$ @ $V_{GS} = 2.5\text{V}$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired
- ESD Protected: 2KV

Application

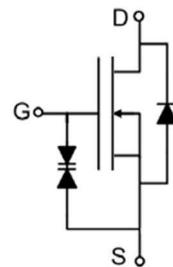
- Load Switch
- PWM Application
- Power management



SOT-523 top view



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

| Device Marking | Device | OUTLINE | Device Package | Reel Size | Reel (PCS) | Per Carton (PCS) |
|----------------|-------------|---------|----------------|-----------|------------|------------------|
| 02K | PECJ2002KT5 | TAPING | SOT-523 | - | - | - |

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | | Max. | Units |
|-----------------|---|---------------------------|-------------|---------------------------|
| V_{DSS} | Drain-Source Voltage | | 20 | V |
| V_{GSS} | Gate-Source Voltage | | ± 10 | V |
| I_D | Continuous Drain Current | $T_A = 25^\circ\text{C}$ | 0.75 | A |
| | | $T_A = 100^\circ\text{C}$ | 0.5 | A |
| I_{DM} | Pulsed Drain Current ^{note1} | | 3 | A |
| P_D | Power Dissipation | $T_A = 25^\circ\text{C}$ | 0.15 | W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Case | | 833 | $^\circ\text{C}/\text{W}$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | | -55 to +150 | $^\circ\text{C}$ |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|--|---|------|------|----------|------------------|
| Off Characteristic | | | | | | |
| $V_{(\text{BR})\text{DSS}}$ | Drain-Source Breakdown Voltage | $V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$ | 20 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$, | - | - | 1 | μA |
| I_{GSS} | Gate to Body Leakage Current | $V_{DS}=0\text{V}$, $V_{GS}=\pm 10\text{V}$ | - | - | ± 10 | μA |
| On Characteristics | | | | | | |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$ | 0.3 | 0.65 | 1 | V |
| $R_{DS(\text{on})}$ note2 | Static Drain-Source on-Resistance | $V_{GS}=4.5\text{V}$, $I_D=0.5\text{A}$ | - | 250 | 380 | $\text{m}\Omega$ |
| | | $V_{GS}=2.5\text{V}$, $I_D=0.3\text{A}$ | - | 350 | 450 | |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$ | - | 79 | - | pF |
| C_{oss} | Output Capacitance | | - | 13 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 9 | - | pF |
| Q_g | Total Gate Charge | $V_{DS}=10\text{V}$, $I_D=0.3\text{A}$, $V_{GS}=4.5\text{V}$ | - | 5 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 0.8 | - | nC |
| Q_{gd} | Gate-Drain("Miller") Charge | | - | 1.2 | - | nC |
| Switching Characteristics | | | | | | |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DS}=10\text{V}$, $I_D=0.5\text{A}$, $R_{\text{GEN}}=3\Omega$, $V_{GS}=4.5\text{V}$ | - | 6.7 | - | ns |
| t_r | Turn-on Rise Time | | - | 4.8 | - | ns |
| $t_{d(off)}$ | Turn-off Delay Time | | - | 17.3 | - | ns |
| t_f | Turn-off Fall Time | | - | 7.4 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I_s | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 0.75 | A |
| I_{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 3 | A |
| V_{SD} | Drain to Source Diode Forward Voltage | $V_{GS}=0\text{V}$, $I_s=0.75\text{A}$ | - | - | 1.2 | V |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

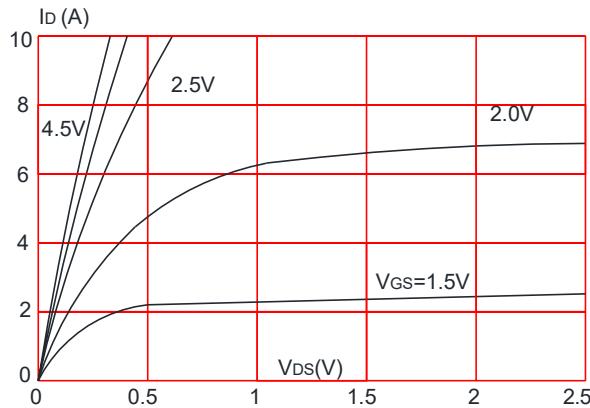


Figure 2: Typical Transfer Characteristics

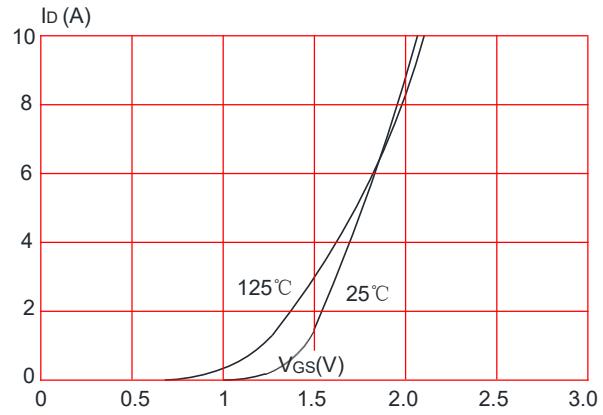


Figure 3: On-resistance vs. Drain Current

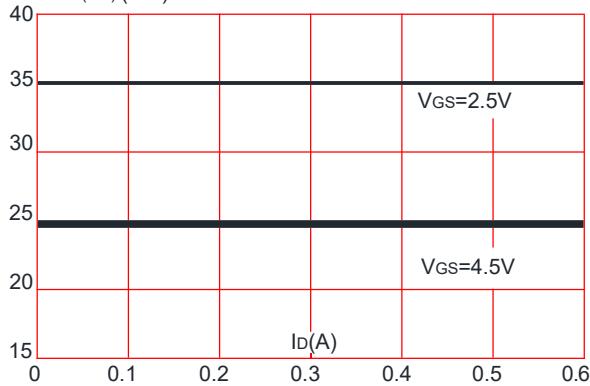


Figure 5: Gate Charge Characteristics

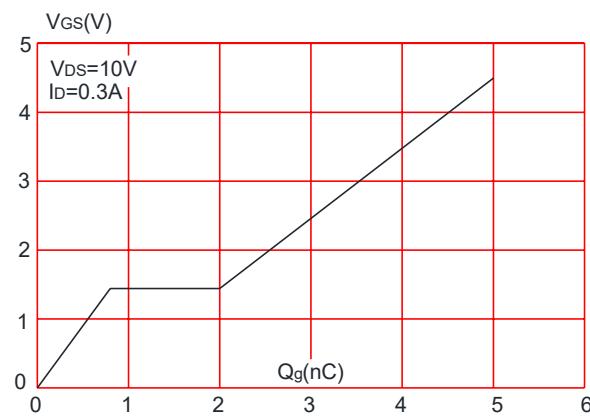


Figure 4: Body Diode Characteristics

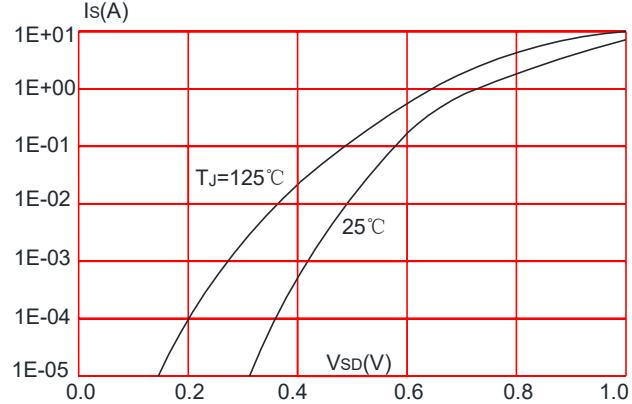


Figure 6: Capacitance Characteristics

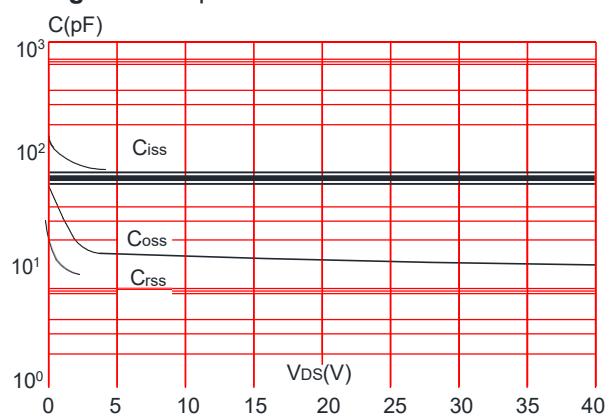


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

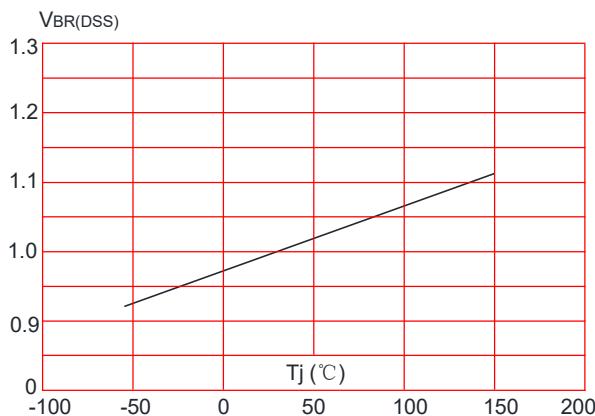


Figure 8: Normalized on Resistance vs. Junction Temperature

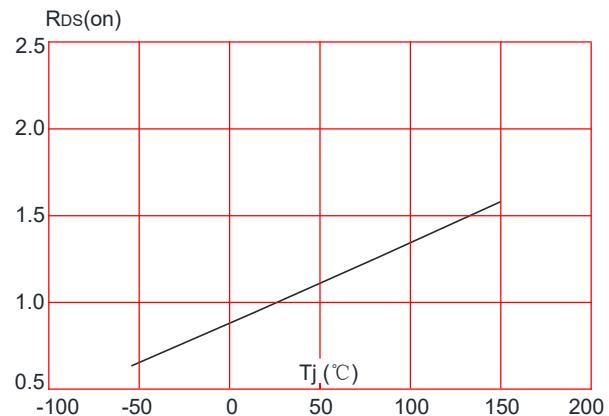


Figure 9: Maximum Safe Operating Area

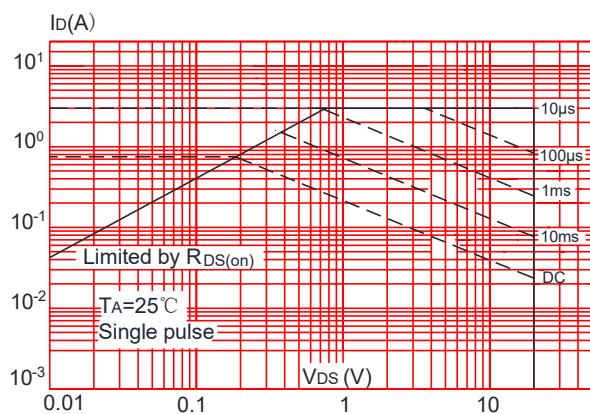


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

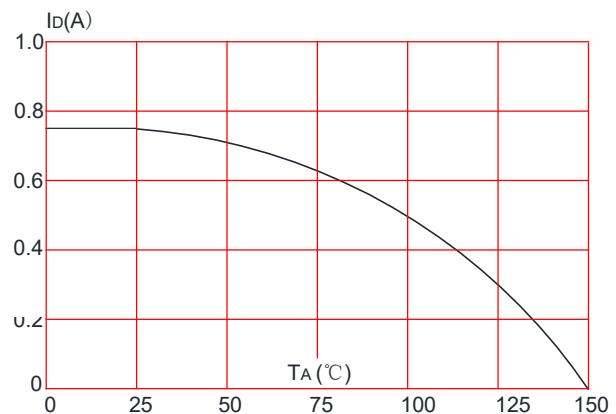
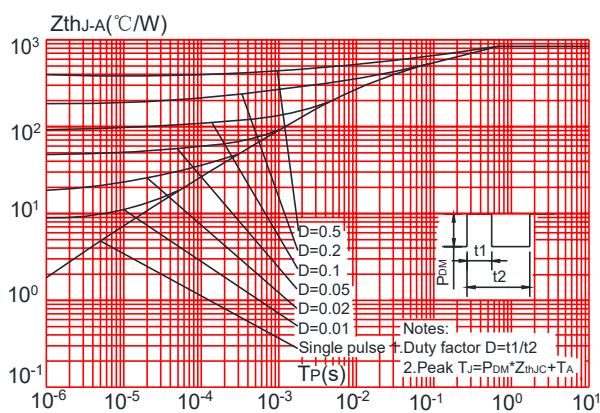


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Test Circuit

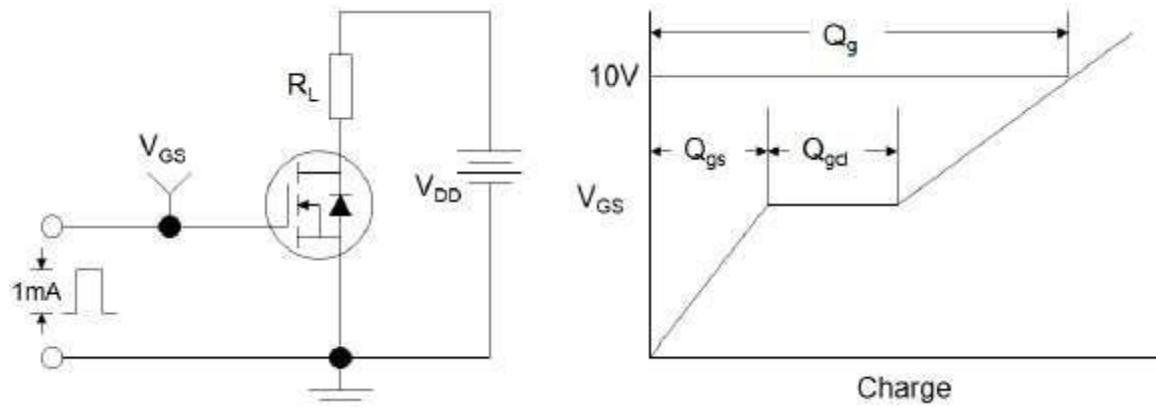


Figure 1: Gate Charge Test Circuit & Waveform

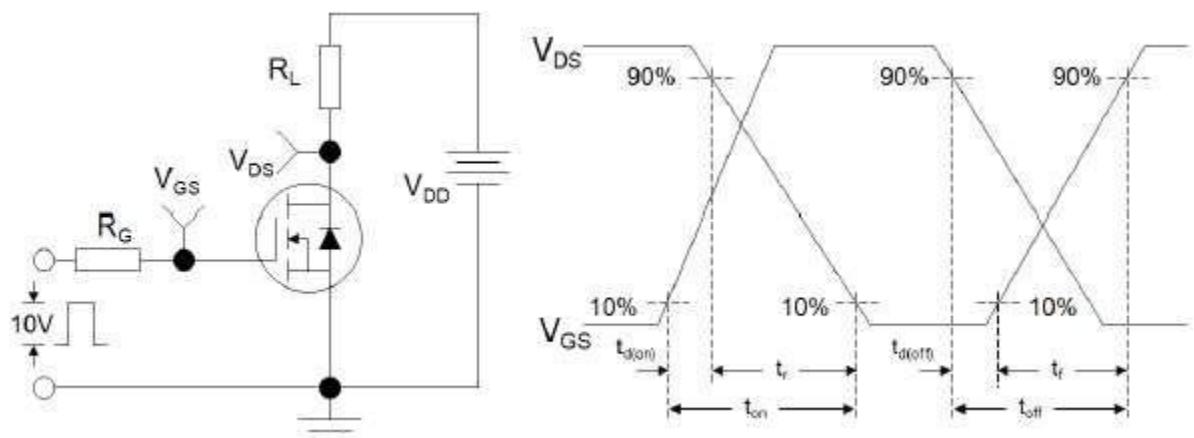


Figure 2: Resistive Switching Test Circuit & Waveforms

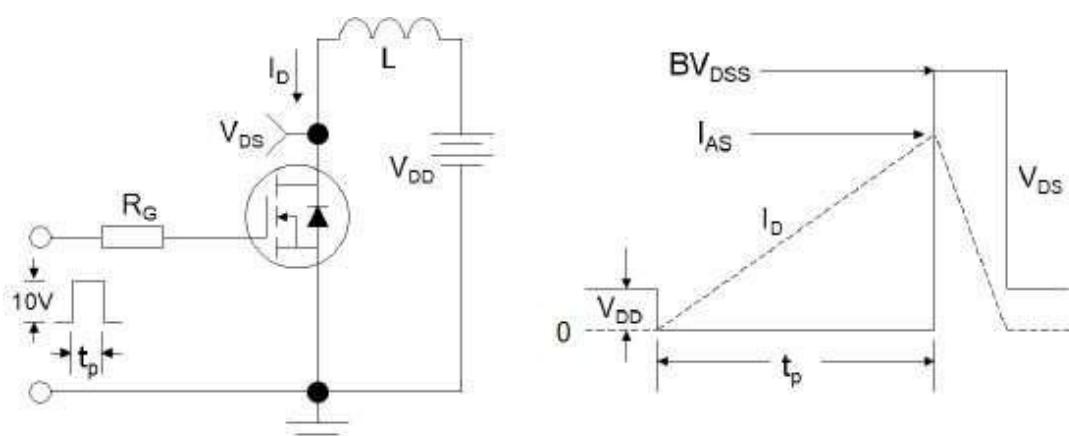
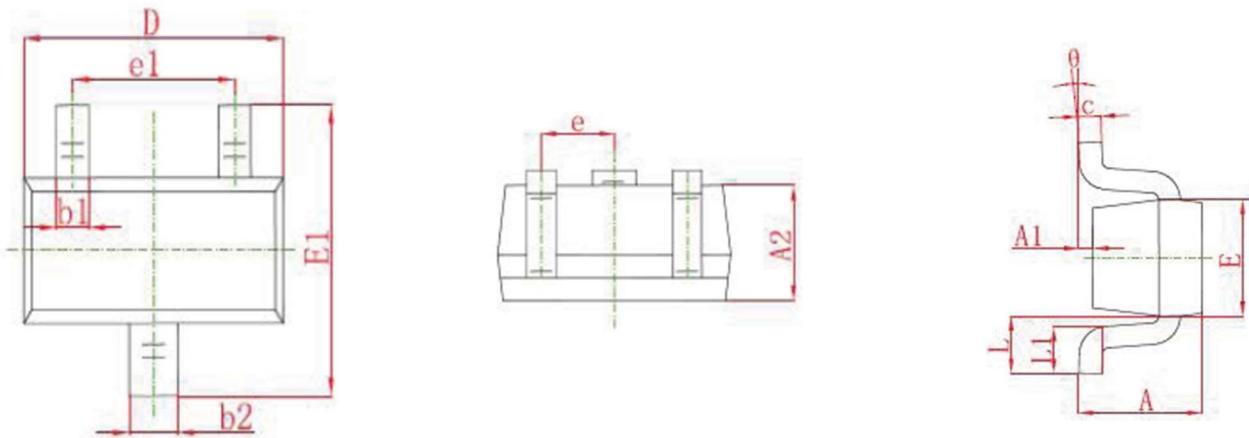


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data-SOT-523



| Symbol | Dimensions In Millimeters | |
|--------|---------------------------|-------|
| | Min. | Max. |
| A | 0.700 | 0.900 |
| A1 | 0.000 | 0.100 |
| A2 | 0.700 | 0.800 |
| b1 | 0.150 | 0.250 |
| b2 | 0.250 | 0.350 |
| c | 0.100 | 0.200 |
| D | 1.500 | 1.700 |
| E | 0.700 | 0.900 |
| E1 | 1.450 | 1.750 |
| e | 0.500 TYP | |
| e1 | 0.900 | 1.100 |
| L | 0.400 REF | |
| L1 | 0.260 | 0.460 |
| θ | 0° | 8° |